
ASP-DAC 2006

Session 8C-5: Inductive Issues in Power Grids and Packages

Controlling Inductive Cross-talk and Power in Off-chip Buses using CODECs

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Motivation

- **Power delivery is the biggest challenge facing designers entering DSM**
 - The IC core current continues to increase ($P_4 = 80\text{Amps}$).
 - The package interconnect inductance limits instantaneous current delivery.
 - The inductance leads to ground and power supply bounce.
- **SSN on signal pins is the leading cause of inter-chip bus failure**
 - Ground/power supply bounce causes unwanted switching.
 - Mutual Inductive cross-talk causes edge degradation which limits speed.
 - Mutual Inductive cross-talk causes glitches which results in unwanted switching.
- **Further, power in off-chip buses can be significant.**
 - Large percentage of power may be consumed in the output stages
- **Aggressive package design helps, but is too expensive:**
 - Flip-Chip technology can reduce the interconnect inductance.
 - Flip-Chip requires a unique package design for each ASIC.
 - This leads to longer process time which equals cost.
 - 90% of ASIC design starts use wire-bonding due to its low cost.
 - Wire-bonding has large parasitic inductance that must be addressed.

Our Solution

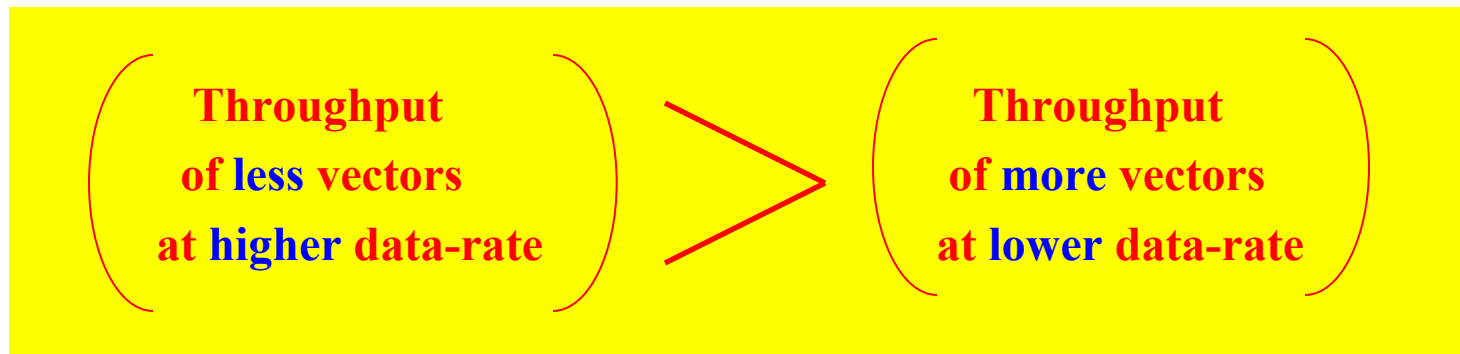
“Encode Off-Chip Data to Avoid Inductive Cross-talk & Power Consumption”

- **Avoid the following cases:**

- 1) **Excessive switching in the same direction** = **reduce ground/power bounce**
- 2) **Excessive X-talk on a signal when switching** = **reduce edge degradation**
- 3) **Excessive X-talk on signal when static** = **reduce glitching**
- 4) **At the same time, limit the number of transitions** = **reduce power**

Our Solution

- This results in:
 - 1) A subset of vectors is transmitted that avoids inductive X-talk & power.
 - 2) The off-chip bus can now be ran at a higher data rate.
 - 3) The subset of vectors running faster can achieve a higher throughput over the original set of vectors running slower.



Agenda

- 1) Inductive X-talk & Power**
- 2) Terminology**
- 3) Methodology**
- 4) Experimental Results**
- 5) Conclusion**

1) Inductive X-Talk

Supply Bounce

- The instantaneous current that flows when signals switch induces a voltage across the inductance of the power supply interconnect following:

$$V_{bnc} = L \cdot \left(\frac{di}{dt} \right)$$

- When more than one signal returns current through one supply pin, the expression becomes:

$$V_{bnc} = L \cdot \sum_j \left(\frac{di}{dt} \right)$$

NOTE: Reducing the number of signals switching in the same direction at the same time will reduce the supply bounce.

1) Inductive X-Talk

Glitching

- Mutual inductive coupling from neighboring signals that are switching cause a voltage to induce on the victim that is static:

$$V_{glitch}^i = \pm M_{ik} \cdot \left(\frac{di_k}{dt} \right)$$

- The net coupling is the summation from all neighboring signals that are switching:

$$V_{glitch}^i = \sum_{k=1}^m \pm M_{ik} \cdot \left(\frac{di_k}{dt} \right) \qquad M_{ik} = K_{ik} \cdot \sqrt{L_i \cdot L_k}$$

NOTE: The mutual inductive coupling can be canceled out when two neighbors of equal K_{ik} switch in opposite directions. Also, K_{ik} is the mutual inductive coupling coefficient

1) Inductive X-Talk

Edge Degradation

- Mutual inductive coupling from neighboring signals that are switching cause a voltage to be induced on the victim that is also switching. This follows the same expression as glitch coupling:

$$V_{glitch} = \sum_1^k \pm M_{1k} \cdot \left(\frac{di_k}{dt} \right)$$

- The mutual inductive coupling can be manipulated to cause a positive (negative) glitch for a rising (falling) signal.
- Mutual coupling can thus be exploited so as to *help* the transition resulting in a faster rise-time or fall-time (alternately, to *not hinder* the risetime of the transition)

1) Power

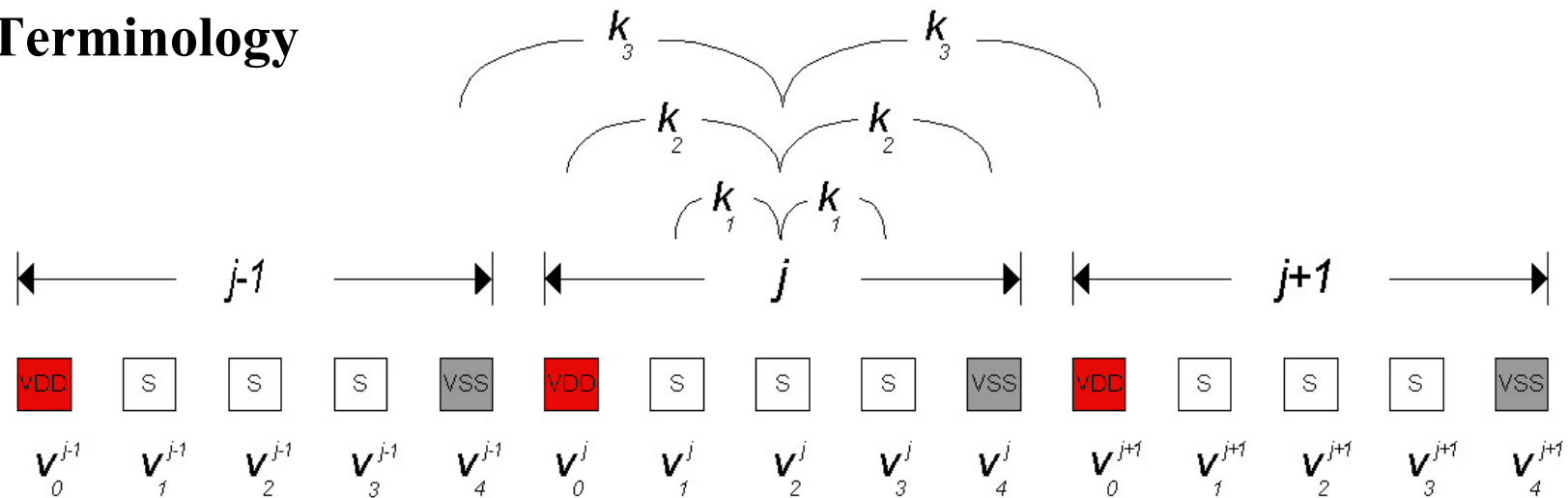
Power Consumption

- The power consumed in the output stage is proportional to the capacitance being driven, the output voltage swing, and the switching frequency.

$$P_{pin} = C \cdot V_{DD}^2 \cdot f$$

NOTE: Power is proportional to the number of switching pins.

2) Terminology

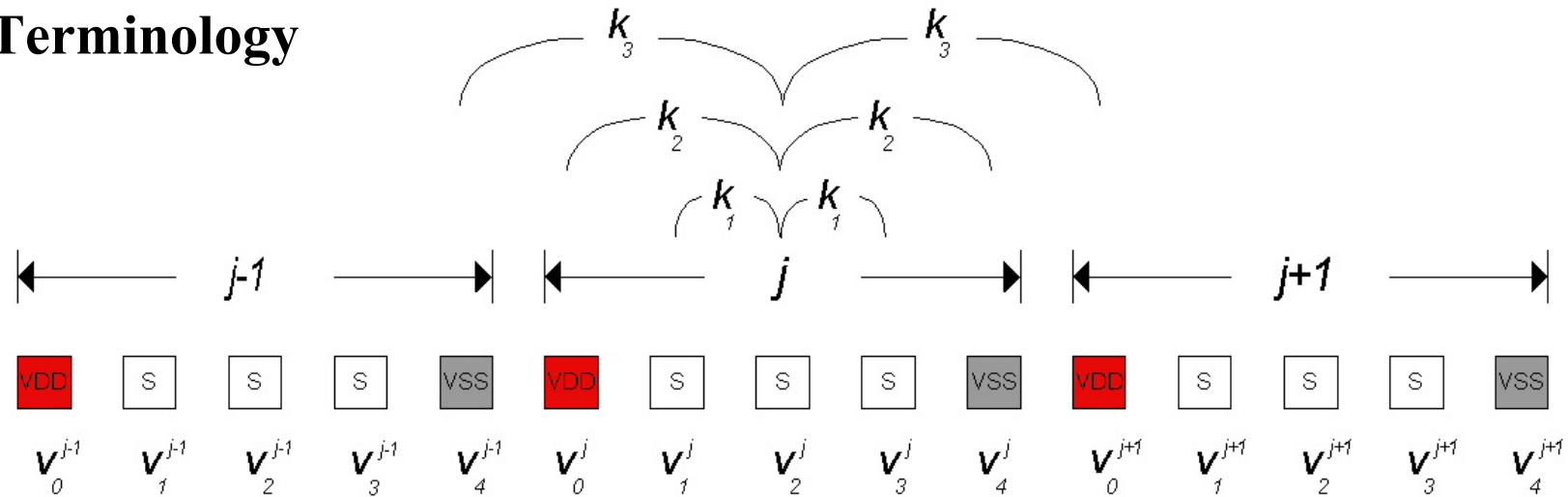


Define the following:

n = width of the bus segment
 where each bus segment consists of $n-2$ signals
 and 1 VDD and 1 VSS.

j = the segment consisting of an n -bit bus.
 j is the segment under consideration.
 $j-1$ is the segment to the immediate left.
 $j+1$ is the segment to the immediate right.
 each segment has the same VDD/VSS placement.

2) Terminology



Define the following:

$v_i^j =$ the transition (vector sequence) that the i^{th} signal in the j^{th} segment is undergoing, where

$$\begin{aligned} v_i^j &= 1 = \text{rising edge} \\ v_i^j &= -1 = \text{falling edge} \\ v_i^j &= 0 = \text{signal is static} \end{aligned}$$

This 3-valued algebra enables us to model mutual inductive coupling of any sign

2) Terminology

Define the following coding constraints:

Supply Bounce

if v_i^j is a supply pin, the total bounce on this pin is bounded by P_{bnc} .
 P_{bnc} is a user defined constant.

Glitching

if v_i^j is a signal pin and is static ($v_i^j = 0$), the total magnitude of the glitch from switching neighbors should be less than P_0 . P_0 is a user defined constant.

Edge Degradation

if v_i^j is a signal pin and is switching ($v_i^j = 1/-1$), the total magnitude of the coupling from switching neighbors should be greater than P_1/P_{-1} . This coupling should not hurt (should aid) the transition. P_1/P_{-1} is a user defined constant.

2) Terminology - Power

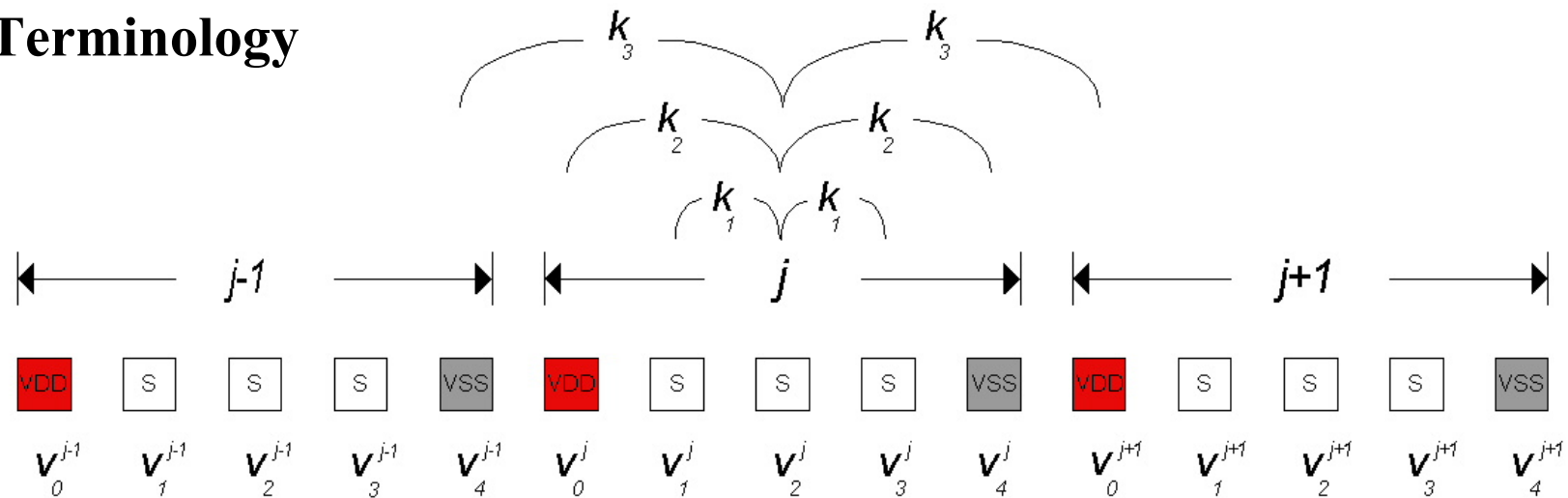
Define the following coding constraints:

Power

for a given segment j , the total power consumption on that segment is bounded by P_{power} .

P_{power} is a user defined constant.

2) Terminology



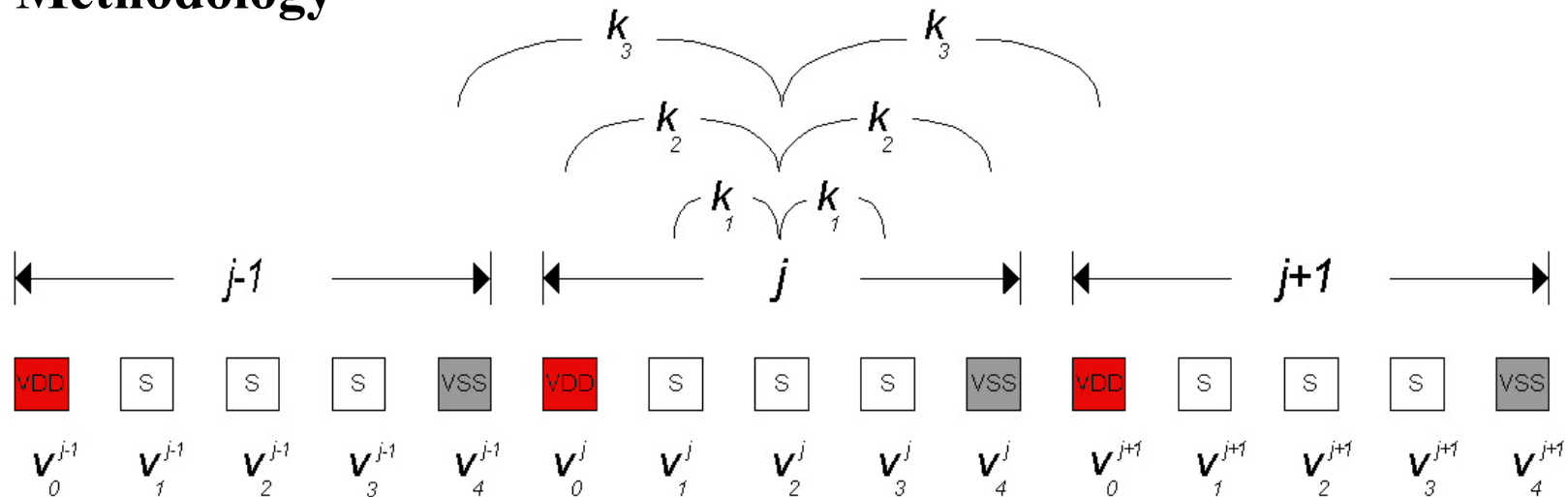
Also define the following:

$p =$ how far away to consider coupling
(ex., $p = 3$, consider K_{11} , K_{12} , and K_{13} on each side of the victim)

$k_q =$ Magnitude of coupled voltage on pin i when its q^{th} neighbor p switches:

$$k_q = \left| M_{ip} \cdot \left(\frac{di_p}{dt} \right) \right|$$

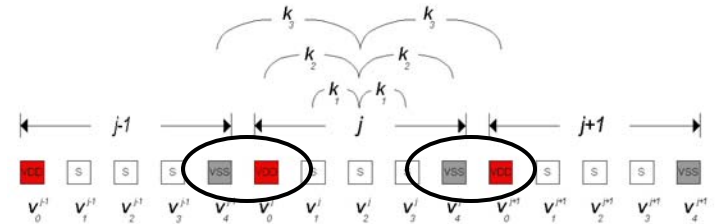
3) Methodology



- For each pin v_i^j within segment j , we will write a series of constraints that will bound the inductive cross-talk magnitude.
- The constraints will differ depending on whether v_i^j is a signal or power pin.
- The coupling constraints will consider signals in adjacent segments ($j+1, j-1$) depending on p .

3) Methodology – Signal Pin Constraints

Glitching : coupling is bounded by P_0



Example:

$v_2^j = 0$, and $p=3$. This means the three adjacent neighbors on either side of v_2^j need to be considered (v_4^{j-1} , v_0^j , v_1^j , v_3^j , v_4^j , v_0^{j+1}).

Note we use *modulo n* arithmetic (and consider adjacent segments as required).

$$v_2^j = 0 \text{ (static)} \quad \begin{matrix} \nearrow 0 \\ \nearrow 0 \\ \nearrow 0 \\ \nearrow 0 \end{matrix}$$

$$-P_0 \leq \cancel{k_3 \cdot (v_4^{j-1})} + \cancel{k_2 \cdot (v_0^j)} + k_1 \cdot (v_1^j) + k_1 \cdot (v_3^j) + \cancel{k_2 \cdot (v_4^j)} + \cancel{k_3 \cdot (v_0^{j+1})} \leq P_0$$

The constraint equation is tested against each possible transition and the transitions that violate the constraint are eliminated.

3) Methodology – Signal Pin Constraints

Edge Degradation : coupling is bounded by P_1 and P_{-1}

Example:

$v_2^j = 1$ or -1 , and $p = 3$. This means the three adjacent neighbors on either side of v_2^j need to be considered (v_4^{j-1} , v_0^j , v_1^j , v_3^j , v_4^j , v_0^{j+1}).

$v_2^j = 1$ (rising)

$$k_3 \cdot \cancel{(v_4^{j-1})}^0 + k_2 \cdot \cancel{(v_0^j)}^0 + k_1 \cdot (v_1^j) + k_1 \cdot (v_3^j) + k_2 \cdot \cancel{(v_4^j)}^0 + k_3 \cdot \cancel{(v_0^{j+1})}^0 \geq P_1$$

$v_2^j = -1$ (falling)

$$k_3 \cdot \cancel{(v_4^{j-1})}^0 + k_2 \cdot \cancel{(v_0^j)}^0 + k_1 \cdot (v_1^j) + k_1 \cdot (v_3^j) + k_2 \cdot \cancel{(v_4^j)}^0 + k_3 \cdot \cancel{(v_0^{j+1})}^0 \leq P_{-1}$$

Again, the constraint equations are tested against each possible transition and the transitions that violate the constraints are eliminated.

3) Methodology – Power Pin Constraints

Supply Bounce : coupling is bounded by P_{bnc}

Example:

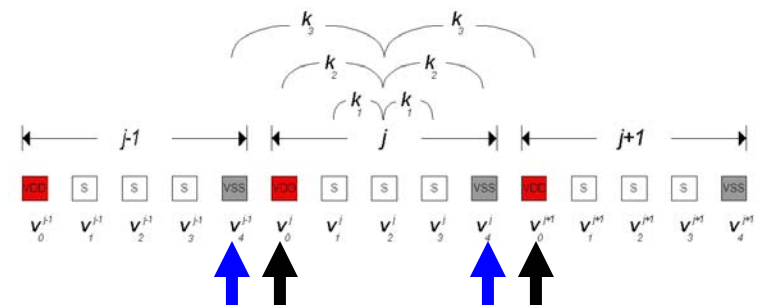
$v_0^j = V_{DD}$ or V_{SS} . The total number of switching signals that use v_0^j to return current must be considered. Due to symmetry of the bus arrangement, signal pins will always return current through two supply pins. i.e., $(v_0^{j-1}$ and $v_0^j)$ or $(v_4^j$ and $v_4^{j+1})$. This results in the self inductance of the return path being divided by 2. Let $z = |L di/dt|$ for any pin. Then,

$$v_0^j = V_{DD}$$

$$(z/2) \cdot (\# \text{ of } v_i^j \text{ pins that are 1}) \leq P_{bnc}$$

$$v_4^j = V_{SS}$$

$$(z/2) \cdot (\# \text{ of } v_i^j \text{ pins that are -1}) \leq P_{bnc}$$



3) Methodology – Power Constraints

Power Consumption : consumption is bounded by P_{power}

Example:

For segment j . The total number of switching signals can be constrained to reduce power.

Segment j

$$(\# \text{ of } v_i^j \text{ pins that are 1 or -1}) \leq P_{power}$$

3) Methodology – Constructing Legal Vectors Sequences

- For each bit in the j^{th} segment bus, constraints are written.
- If the pin is a signal, 3 constraint equations are written;
 - $v_o^j = 0$, the bit is **static** and a *glitching constraint* is written
 - $v_o^j = 1$, the bit is **rising** and an *edge degradation* constraint is written.
 - $v_o^j = -1$, the bit is **falling** and an *edge degradation* constraint is written.
- If the pin is **VDD**, 1 constraint equation is written to avoid *supply bounce*.
- If the pin is **VSS**, 1 constraint equation is written to avoid *ground bounce*.
- For the segment, 1 constraint equation is written to constrain *power*.

3) Methodology – Constructing Legal Vectors Sequences

- This results in the total number of constraint equations written is:

$$(3 \cdot n - 3)$$

- Each equation must be evaluated for each possible transition to verify if the transition meets the constraints. The total number of transitions that are evaluated depends on n and p :

$$3^{(n+2p-6)}$$

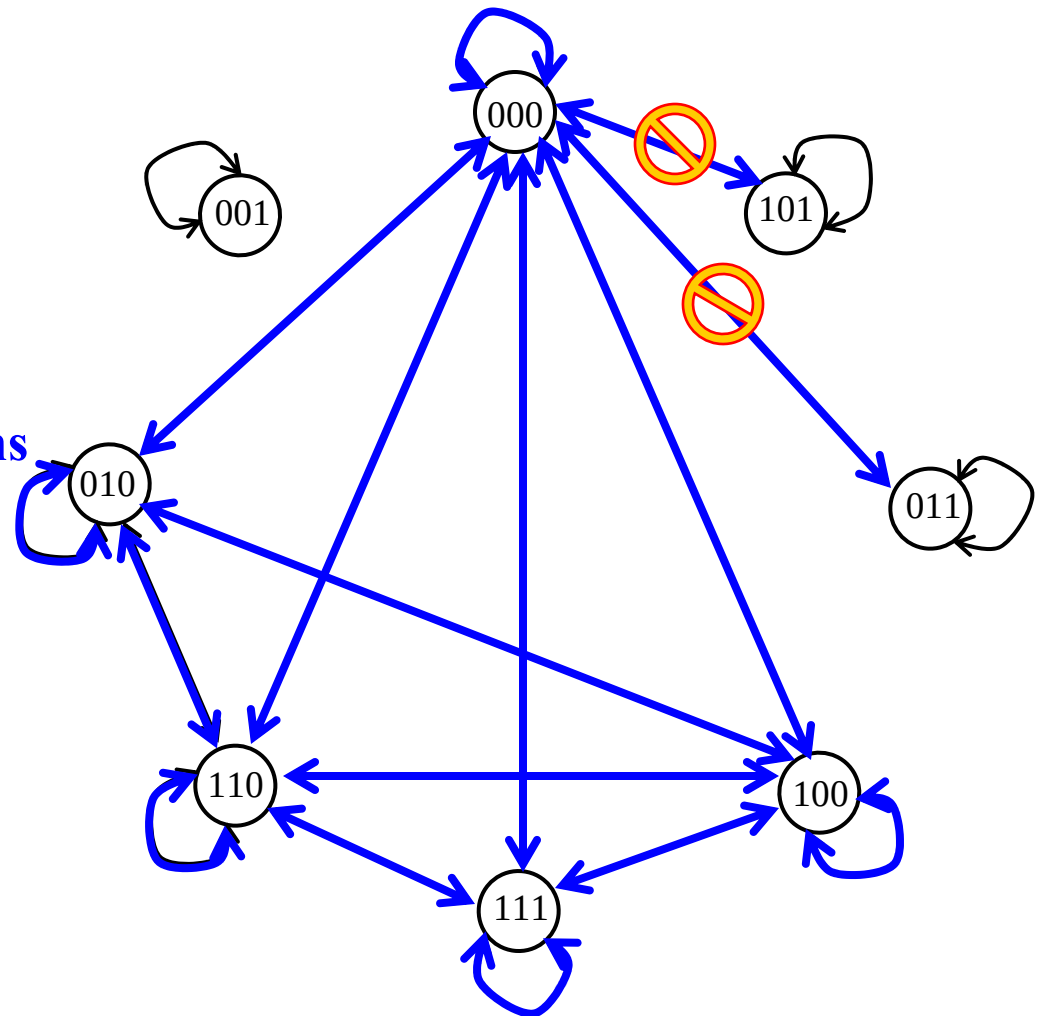
- This follows since there are $n-2$ signal pins in the segment j , and $2p-4$ signal pins in neighboring segments.
- The values of n and p are small in practice, hence this is tractable.

3) Methodology – Constructing the CODEC

- The remaining legal transitions are used to create the CODEC.
- The total number of remaining legal transitions will depend on how aggressive the user-defined constants are chosen ($P_0, P_1, P_{-1}, P_{bnc}, P_{power}$)
- From the remaining legal transitions, find the effective bus width m that can be encoded using a physical bus of width n , using a memory-based CODEC.
 - Utilize a fixpoint computation

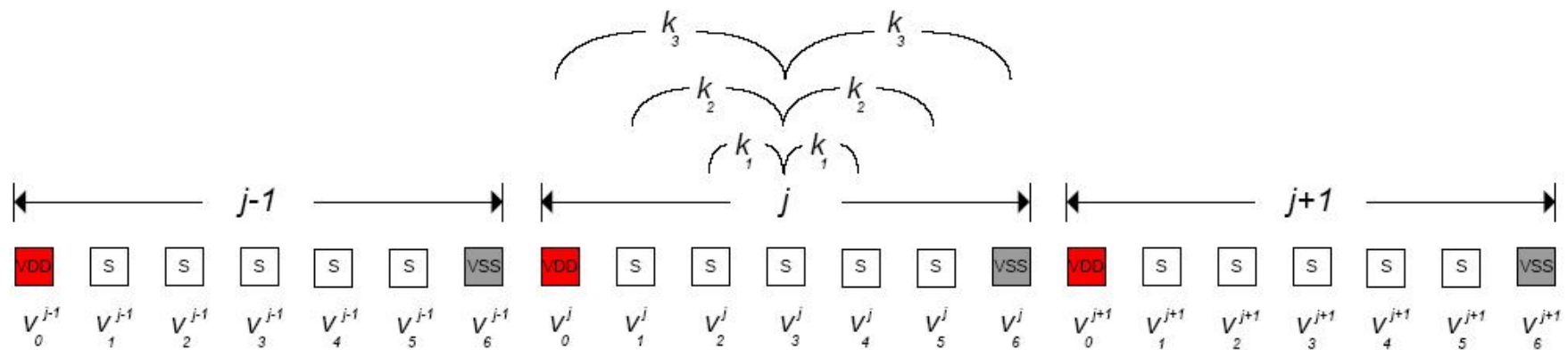
3) Methodology – Constructing the CODEC

- Represent remaining legal transitions in a digraph
- Algorithm to find CODEC:
 - Let n = size of physical bus
 - Let m = size of effective bus
 - Then the digraph of legal transitions of the n bit bus can encode an m bit bus ($m < n$) iff
 - We can find a closed set S of nodes such that
 - $|S| \geq 2^m$
 - Each vertex s in S has at least 2^m out-edges (including self-edges) to vertices s' in S
- Now we can synthesize the encoder and decoder (memory based).



4) Experimental Results – 5 Signal Pins

Example Bus: $n=7, p=2$



$P_0, P_1, P_{-1}, P_{bnc}$

Aggressive Encoding

Non-Aggressive Encoding

Power Encoding

5% of V_{DD}

12.5% of V_{DD}

20% of Max

4) Experimental Results – Constraint Equations

of Constraints = $(3n - 3) = 12$

- 1) $v_0^j = V_{DD} \rightarrow (L/2) \cdot (\# \text{ of } v_i^j \text{ pins that are } 1) \leq P_{bnc}$**
- 2) $v_1^j = 1 \rightarrow k_1 \cdot (v_2^j) + k_2 \cdot (v_3^j) \geq P_1$**
- 3) $v_1^j = -1 \rightarrow k_1 \cdot (v_2^j) + k_2 \cdot (v_3^j) \leq P_{-1}$**
- 4) $v_1^j = 0 \rightarrow -P_0 \leq k_1 \cdot (v_2^j) + k_2 \cdot (v_3^j) \leq P_0$**
- 5) $v_2^j = 1 \rightarrow k_1 \cdot (v_1^j) + k_1 \cdot (v_3^j) \geq P_1$**
- 6) $v_2^j = -1 \rightarrow k_1 \cdot (v_1^j) + k_1 \cdot (v_3^j) \leq P_{-1}$**
- 7) $v_2^j = 0 \rightarrow -P_0 \leq k_1 \cdot (v_1^j) + k_1 \cdot (v_3^j) \leq P_0$**
- 8) $v_3^j = 1 \rightarrow k_2 \cdot (v_1^j) + k_1 \cdot (v_2^j) \geq P_1$**
- 9) $v_3^j = -1 \rightarrow k_2 \cdot (v_1^j) + k_1 \cdot (v_2^j) \leq P_{-1}$**
- 10) $v_3^j = 0 \rightarrow -P_0 \leq k_2 \cdot (v_1^j) + k_1 \cdot (v_2^j) \leq P_0$**
- 11) $v_4^j = V_{SS} \rightarrow (L/2) \cdot (\# \text{ of } v_i^j \text{ pins that are } -1) \leq P_{bnc}$**
- 12) $(\# \text{ of } v_i^j \text{ pins that are } -1 \text{ or } 1) \leq P_{power}$**

4) Experimental Results – CASE 1: Fixed di/dt

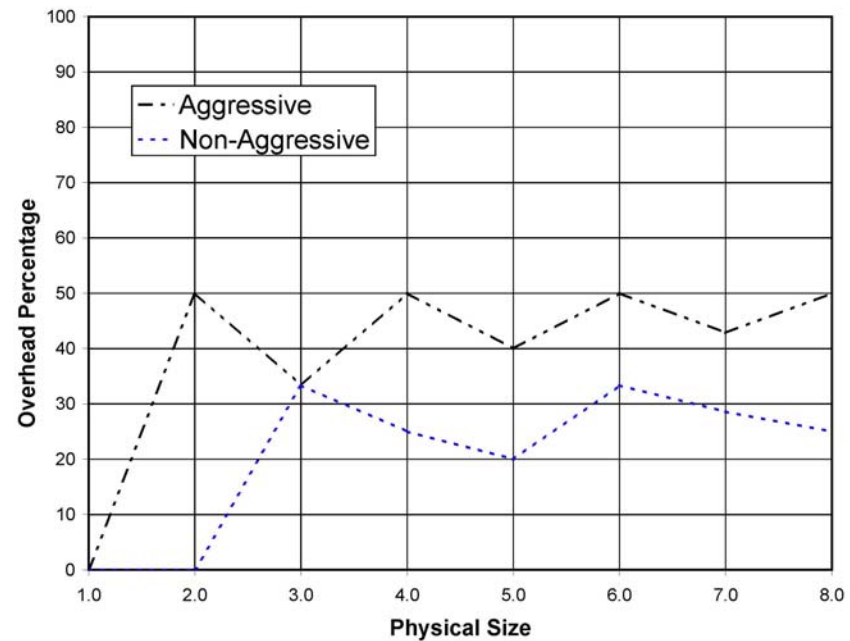
Transitions Eliminated due to Rule Violations

<u>Transition</u>	<u>Rule(s) Violated</u>	
	<u>Aggressive</u>	<u>Non Aggressive</u>
011	violates 1,4	-
0-1-1	violates 4,11	-
101	violates 1,7	-
110	violates 1,10	-
111	violates 1,2,5,8	violates 11
11-1	violates 1	-
1-11	violates 1	-
1-1-1	violates 11	-
-10-1	violates 7,11	-
-111	violates 1	-
-11-1	violates 11	-
-1-10	violates 10,11	-
-1-11	violates 11	-
-1-1-1	violates 3,6,9,11	violates 1

4) Experimental Results – CASE 1: Fixed di/dt

- Encoded data avoids Inductive X-talk pattern

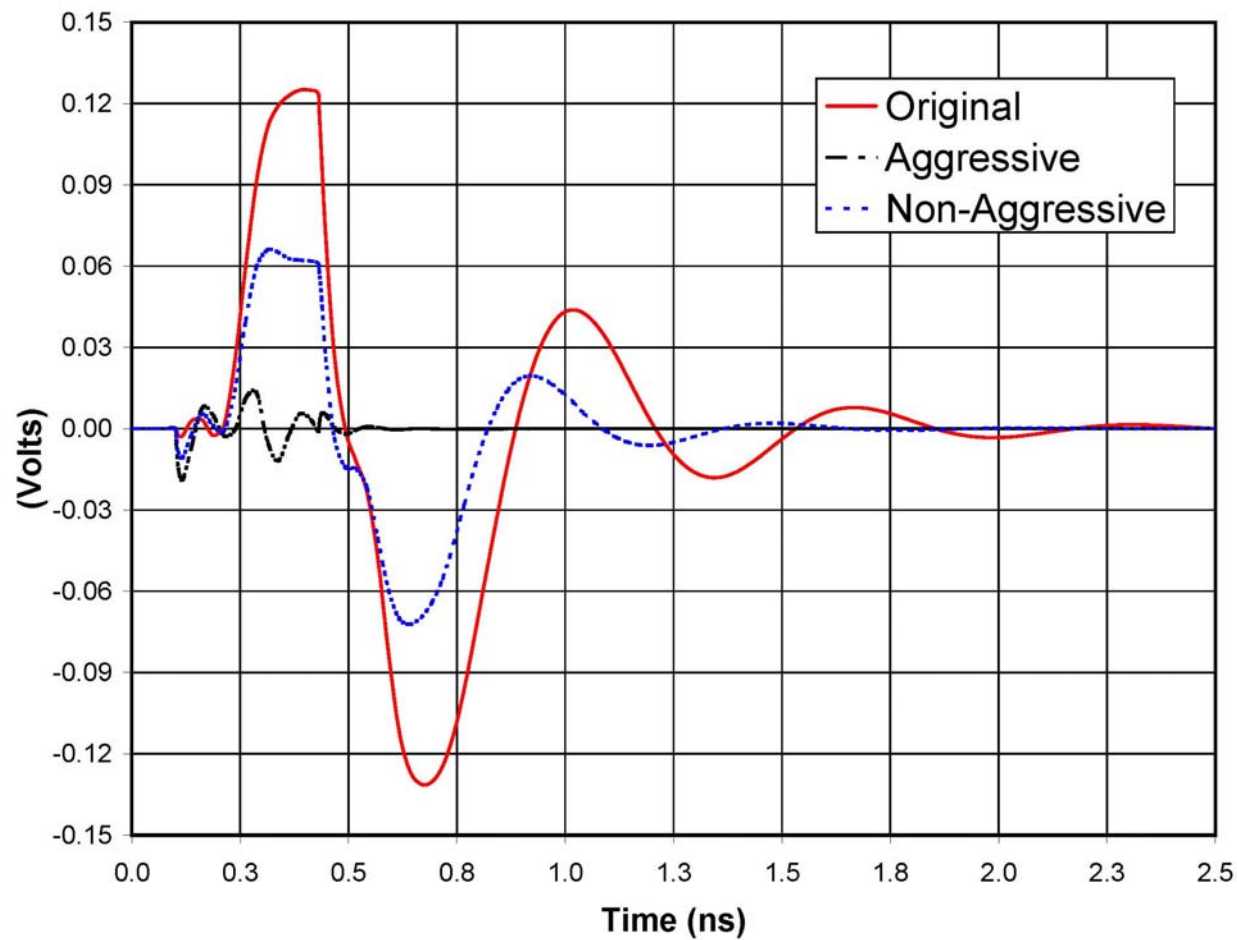
$$\text{Overhead} = 1 - \frac{\text{Effective}}{\text{Physical}} = \frac{n - m}{m}$$



- Bus can be ran faster

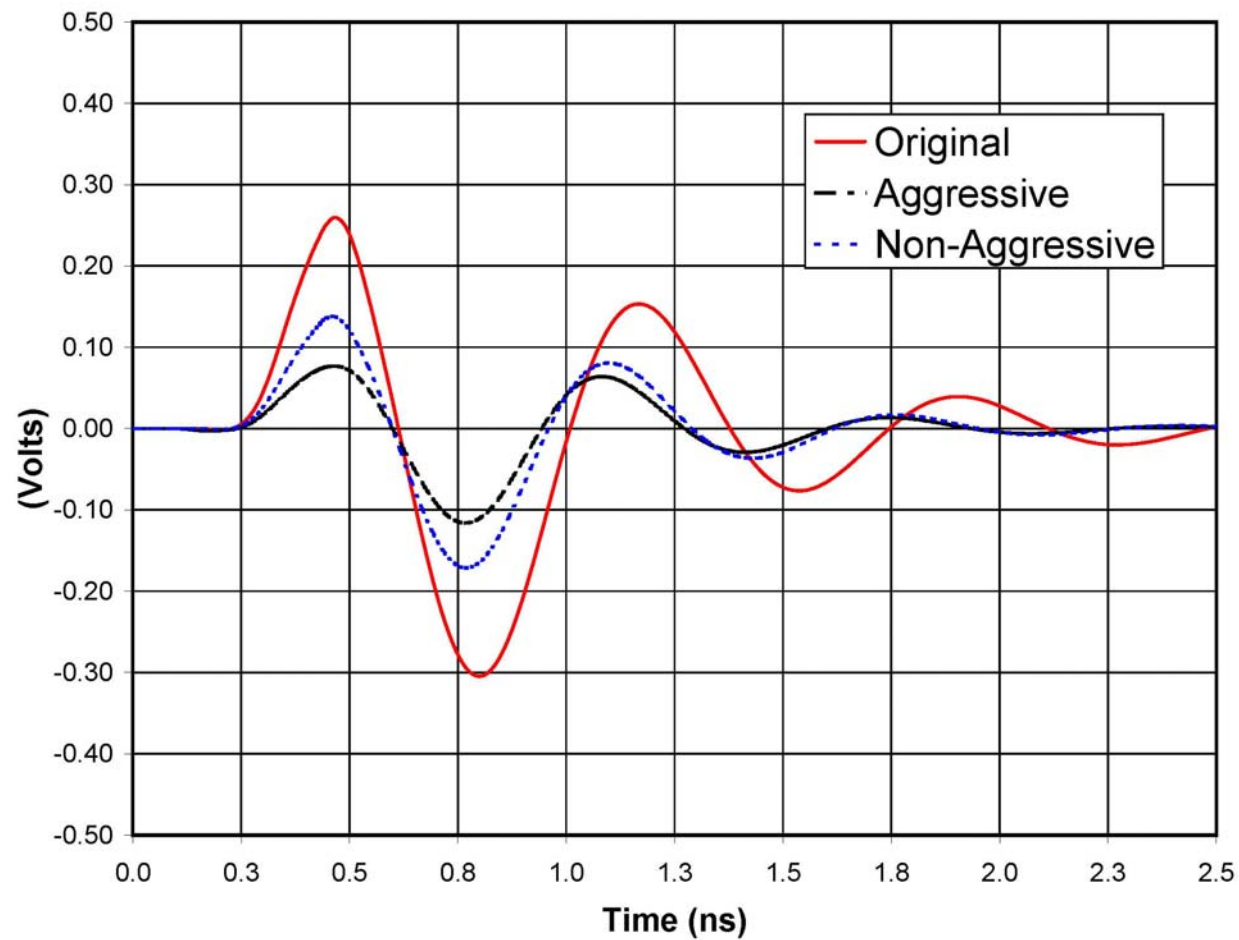
4) Experimental Results – CASE 1: Fixed di/dt

Ground Bounce Simulation



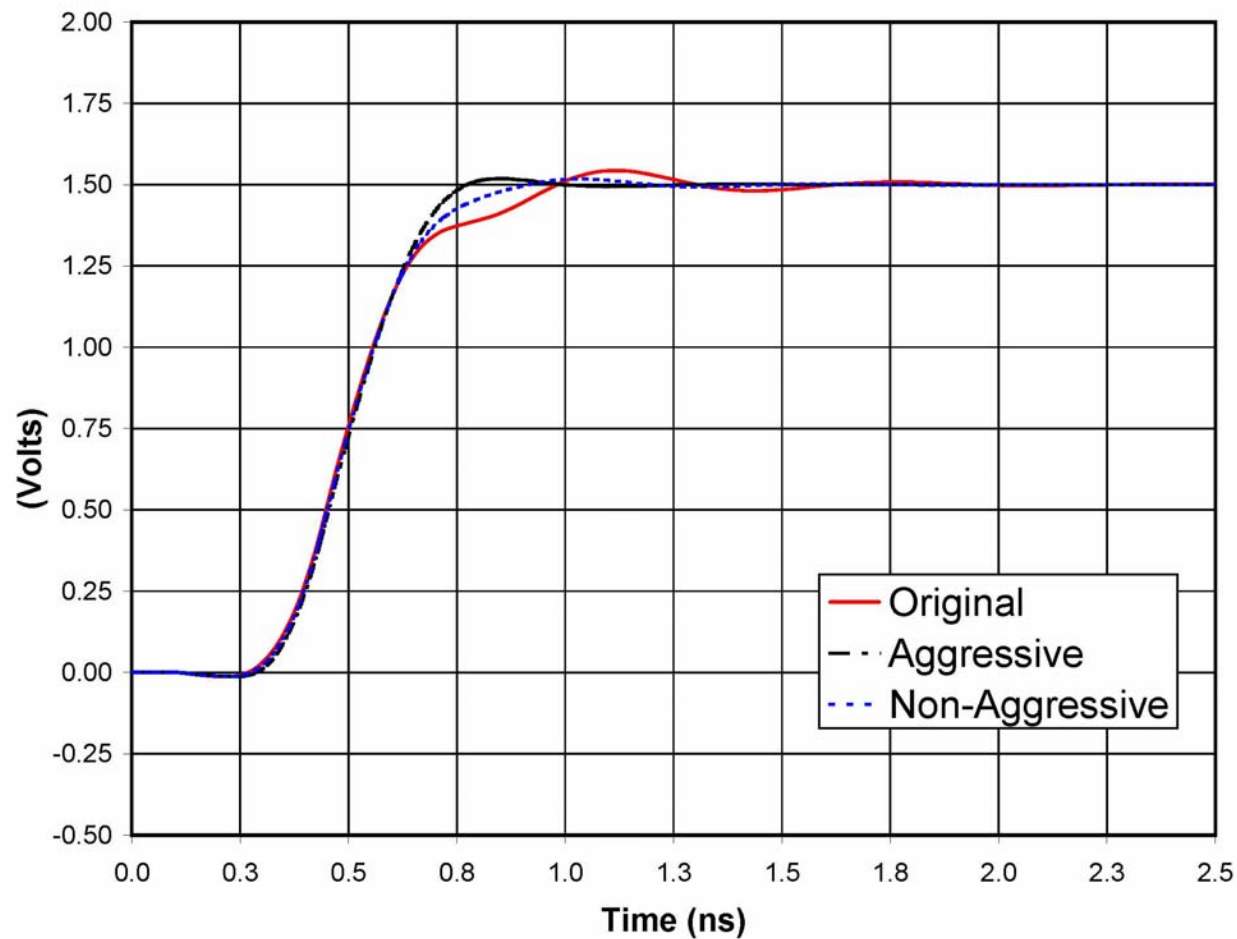
4) Experimental Results – CASE 1: Fixed di/dt

Glitch Simulation



4) Experimental Results – CASE 1: Fixed di/dt

Edge Degradation Simulation



4) Experimental Results – CASE 2: Variable di/dt

- di/dt was swept for both the non-encoded and encoded configuration.
- the maximum di/dt was recorded that resulted in a failure.
- Failure : 5% of VDD (**Aggressive**) and 12.5% of VDD (**Non-Aggressive**)
- the maximum di/dt was converted to data rate and throughput.

	<u>Original</u>	<u>Aggressive</u>	<u>Non-Aggr</u>
Maximum di/dt:	8 MA/s	19.9 MA/s	37 MA/s
Maximum data-rate per pin:	133 Mb/s	333 Mb/s	667 Mb/s
Effective bus width:	5	4	2
Total Throughput:	667 Mb/s	1332 Mb/s	1332 Mb/s
Improvement	-	100%	100%
Power Constraint (% of Max)	100%	20%	20%

4) Experimental Results – ASIC Synthesis

- A 0.13um, TSMC ASIC process was used.
- Delay and Area Extracted

	Bus Size (<i>m</i>)	Style	
	-	aggressive	non-aggressive
Delay (<i>ns</i>)	2	0.170	N/A
	4	0.670	0.503
	6	1.150	0.955
	8	1.310	0.983
Area (<i>um</i> ²)	2	22	N/A
	4	152	114
	6	614	509
	8	1,181	886

4) Experimental Results – FPGA Implementation

- A Xilinx, Virtex-II, 0.35um, FPGA was used.
- Delay and Area Extracted

	Bus Size (m)	Style
	-	aggressive & non-aggressive
Delay (ns)	2	0.351
	4	1.020
	6	1.450
	8	1.610
FPGA Usage	2	< 1%
	4	< 1%
	6	< 1%
	8	< 1%
FPGA Implementation	2	3x, 2-Input FG's
	4	6x, 4-Input FG's
	6	9x, 6-Input FG's
	8	12x, 8-Input FG's

5) Conclusion

- **Using a single mathematical framework, inductive X-talk & power constraints can be written that consider supply bounce, glitching, and edge degradation.**
- **This technique can be used to encode off-chip data transmission to reduce inductive X-talk & power to acceptable levels.**
- **It was demonstrated that even after reducing the effective bus size, the improvement in per pin data-rate resulted in an *increase* in throughput compared to a non-encoded bus.**

Thank you!